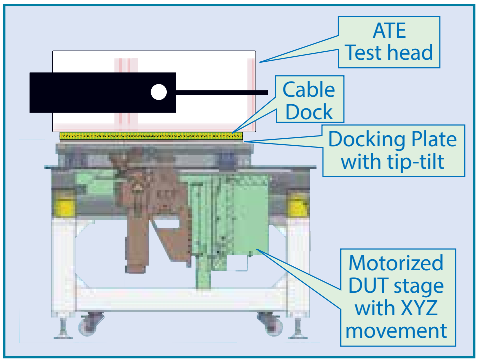
SEMICAPS 3000
DIRECT TESTER-DOCKED SYSTEM

Dynamic
Device
Analysis

photos are for illustration only

Features

- For backside analysis of wafers, wafer parts and packaged devices. Able to dock with all ATE platforms
- Easily moved from Tester to Tester
- Custom docking for all ATE platforms
- High resolution stage with 0.5 µm repeatability
- Aplanatic Refractive Solid Immersion Lens (ARSIL) option, currently probing 3nm nodes
- CAD interface option
- AuriCool option (>200W TDP heat management)
- Analysis Methodologies include a combination of:
  - Laser Timing Probe (LTP)
  - Scanning Optical Microscopy (SOM) with best sensitivity for
    static analysis: TIVA, OBIRCH
    dynamic analysis: LADA, SDL
  - Photon Emission Microscopy (PEM) with various options for the InGaAs or Si-CCD camera
  - Thermal Microscopy (THM)



ATE-Docked

SEMICAPS
Excellence In Innovation

SEMICAPS Pte Ltd
A Company of ***SEMICAPS*** *Corporation Group*

Email: sales@semicaps.com https://www.semicaps.com